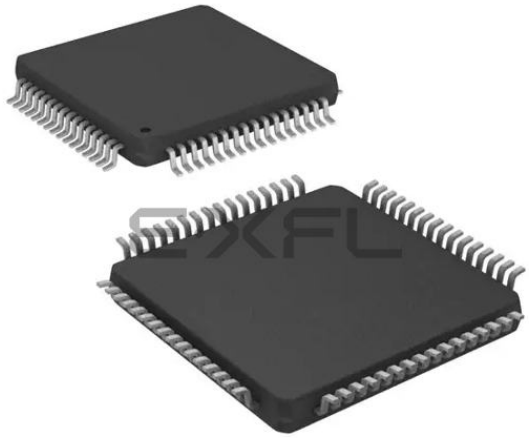
Microchip Technology - PIC32MX470F512H-120/PT Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	49
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx470f512h-120-pt

TABLE 1: PIC32MX330/350/370/430/450/470 CONTROLLER FAMILY FEATURES

Device	Pins	Packages	Program Memory (KB)(1)	Data Memory (KB)	Remappable Peripherals					10-bit 1 Msps ADC (Channels)	Analog Comparators	USB On-The-Go (OTG)	CTMU	I^2C	PMP	RTCC	DMA Channels (Programmable/Dedicated)	I/O Pins	JTAG	Trace
					Remappable Pins	Timers/Capture/Compare(2)	UART	SPI/I^2S	External Interrupts(3)											
PIC32MX330F064H	64	QFN, TQFP	64+12	16	37	5/5/5	4	2/2	5	28	2	N	Y	2	Y	Y	4/0	53	Y	N
PIC32MX330F064L	100	TQFP	64+12	16	54	5/5/5	5	2/2	5	28	2	N	Y	2	Y	Y	4/0	85	Y	Y
	124	VTLA																		
PIC32MX350F128H	64	QFN, TQFP	128+12	32	37	5/5/5	4	2/2	5	28	2	N	Y	2	Y	Y	4/0	53	Y	N
PIC32MX350F128L	100	TQFP	128+12	32	54	5/5/5	5	2/2	5	28	2	N	Y	2	Y	Y	4/0	85	Y	Y
	124	VTLA																		
PIC32MX350F256H	64	QFN, TQFP	256+12	64	37	5/5/5	4	2/2	5	28	2	N	Y	2	Y	Y	4/0	53	Y	N
PIC32MX350F256L	100	TQFP	256+12	64	54	5/5/5	5	2/2	5	28	2	N	Y	2	Y	Y	4/0	85	Y	Y
	124	VTLA																		
PIC32MX370F512H	64	QFN, TQFP	512+12	128	37	5/5/5	4	2/2	5	28	2	N	Y	2	Y	Y	4/0	53	Y	N
PIC32MX370F512L	100	TQFP	512+12	128	54	5/5/5	5	2/2	5	28	2	N	Y	2	Y	Y	4/0	85	Y	Y
	124	VTLA																		
PIC32MX430F064H	64	QFN, TQFP	64+12	16	34	5/5/5	4	2/2	5	28	2	Y	Y	2	Y	Y	4/2	49	Y	N
PIC32MX430F064L	100	TQFP	64+12	16	51	5/5/5	5	2/2	5	28	2	Y	Y	2	Y	Y	4/2	81	Y	Y
	124	VTLA																		
PIC32MX450F128H	64	QFN, TQFP	128+12	32	34	5/5/5	4	2/2	5	28	2	Y	Y	2	Y	Y	4/2	49	Y	N
PIC32MX450F128HB (see **Note 4**)	64	QFN, TQFP	128+12	32	34	5/5/5	4	2/2	5	28	2	Y	Y	2	Y	Y	4/2	49	Y	N
PIC32MX450F128L	100	TQFP	128+12	32	51	5/5/5	5	2/2	5	28	2	Y	Y	2	Y	Y	4/2	81	Y	Y
	124	VTLA																		
PIC32MX450F256H	64	QFN, TQFP	256+12	64	34	5/5/5	4	2/2	5	28	2	Y	Y	2	Y	Y	4/2	49	Y	N
PIC32MX450F256L	100	TQFP	256+12	64	51	5/5/5	5	2/2	5	28	2	Y	Y	2	Y	Y	4/2	81	Y	Y
	124	VTLA																		
PIC32MX470F512H	64	QFN, TQFP	512+12	128	34	5/5/5	4	2/2	5	28	2	Y	Y	2	Y	Y	4/2	49	Y	N
PIC32MX470F512L	100	TQFP	512+12	128	51	5/5/5	5	2/2	5	28	2	Y	Y	2	Y	Y	4/2	81	Y	Y
	124	VTLA																		
PIC32MX470F512LB (see **Note 4**)	100	TQFP	512+12	128	51	5/5/5	5	2/2	5	28	2	Y	Y	2	Y	Y	4/2	81	Y	Y
	124	VTLA																		

Note 1: All devices feature 12 KB of Boot Flash memory.

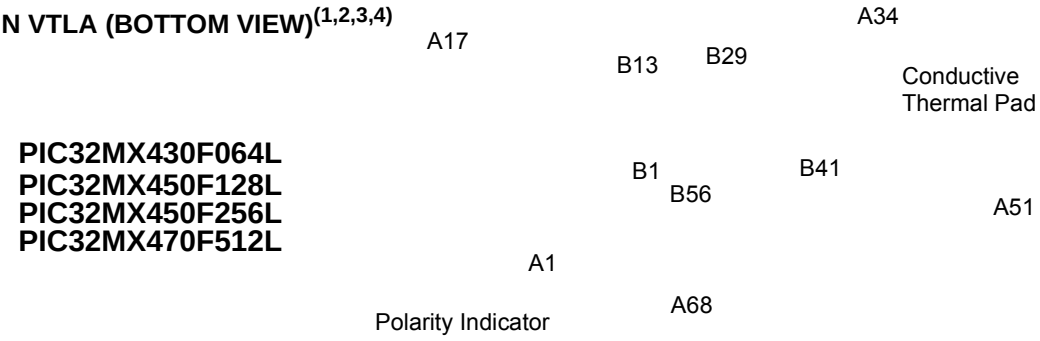
2: Four out of five timers are remappable.

3: Four out of five external interrupts are remappable.

4: This PIC32 device is targeted to specific audio software packages that are tracked for licensing royalty purposes. All peripherals and electrical characteristics are identical to their corresponding base part numbers

TABLE 7: PIN NAMES FOR 124-PIN DEVICES (CONTINUED)

124-PIN VTLA (BOTTOM VIEW)(1,2,3,4)



Package Bump #	Full Pin Name	Package Bump #	Full Pin Name
B7	$\overline{MCLR}$	B32	SDA2/RA3
B8	VSS	B33	TDO/RA5
B9	TMS/CTED1/RA0	B34	OSC1/CLKI/RC12
B10	RPE9/RE9	B35	No Connect
B11	AN4/C1INB/RB4	B36	SCL1/RPA14/RA14
B12	VSS	B37	RPD8/RTCC/RD8
B13	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	B38	RPD10/SCK1/PMCS2/RD10
B14	PGED1/AN0/RPB0/RB0	B39	RPD0/INT0/RD0
B15	No Connect	B40	SOSCO/RPC14/T1CK/RC14
B16	PGED2/AN7/RPB7/CTED3/RB7	B41	VSS
B17	VREF+/CVREF+/PMA6/RA10	B42	AN25/RPD2/RD2
B18	AVSS	B43	RPD12/PMD12/RD12
B19	AN9/RPB9/CTED4/RB9	B44	RPD4/PMWR/RD4
B20	AN11/PMA12/RB11	B45	PMD14/RD6
B21	VDD	B46	No Connect
B22	RPF13/RF13	B47	No Connect
B23	AN12/PMA11/RB12	B48	VCAP
B24	AN14/RPB14/CTED5/PMA1/RB14	B49	RPF0/PMD11/RF0
B25	VSS	B50	RPG1/PMD9/RG1
B26	RPD14/RD14	B51	TRCLK/RA6
B27	RPF4/PMA9/RF4	B52	PMD0/RE0
B28	No Connect	B53	VDD
B29	RPF8/RF8	B54	TRD2/RG14
B30	VUSB3V3	B55	TRD0/RG13
B31	D+	B56	RPE3/CTPLS/PMD3/RE3

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx) can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: Shaded package bumps are 5V tolerant.

4: It is recommended that the user connect the printed circuit board (PCB) ground to the conductive thermal pad on the bottom of the package. And to not run non-Vss PCB traces under the conductive thermal pad on the same side of the PCB layout.

Referenced Sources

This device data sheet is based on the following individual sections of the *"PIC32 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note: To access the following documents, refer to the *Documentation > Reference Manuals* section of the Microchip PIC32 website: http://www.microchip.com/pic32.

- **Section 1. "Introduction"** (DS60001127)
- **Section 2. "CPU"** (DS60001113)
- **Section 3. "Memory Organization"** (DS60001115)
- **Section 4. "Prefetch Cache"** (DS60001119)
- **Section 5. "Flash Program Memory"** (DS60001121)
- **Section 6. "Oscillator Configuration"** (DS60001112)
- **Section 7. "Resets"** (DS60001118)
- **Section 8. "Interrupt Controller"** (DS60001108)
- **Section 9. "Watchdog Timer and Power-up Timer"** (DS60001114)
- **Section 10. "Power-Saving Features"** (DS60001130)
- **Section 12. "I/O Ports"** (DS60001120)
- **Section 13. "Parallel Master Port (PMP)"** (DS60001128)
- **Section 14. "Timers"** (DS60001105)
- **Section 15. "Input Capture"** (DS60001122)
- **Section 16. "Output Compare"** (DS60001111)
- **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104)
- **Section 19. "Comparator"** (DS60001110)
- **Section 20. "Comparator Voltage Reference (CV_{REF})"** (DS60001109)
- **Section 21. "Universal Asynchronous Receiver Transmitter (UART)"** (DS60001107)
- **Section 23. "Serial Peripheral Interface (SPI)"** (DS60001106)
- **Section 24. "Inter-Integrated Circuit (I^2C)"** (DS60001116)
- **Section 27. "USB On-The-Go (OTG)"** (DS60001126)
- **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125)
- **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117)
- **Section 32. "Configuration"** (DS60001124)
- **Section 33. "Programming and Diagnostics"** (DS60001129)
- **Section 37. "Charge Time Measurement Unit (CTMU)"** (DS60001167)

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
CVREF-	15	28	A21	I	Analog	Comparator Voltage Reference (Low)
CVREF+	16	29	B17	I	Analog	Comparator Voltage Reference (High)
CVREFOUT	23	34	A24	I	Analog	Comparator Voltage Reference (Output)
C1INA	11	20	A12	I	Analog	Comparator 1 Inputs
C1INB	12	21	B11	I	Analog	
C1INC	5	11	B6	I	Analog	
C1IND	4	10	A7	I	Analog	
C2INA	13	22	A13	I	Analog	Comparator 2 Inputs
C2INB	14	23	B13	I	Analog	
C2INC	8	14	A9	I	Analog	
C2IND	6	12	A8	I	Analog	
C1OUT	PPS	PPS	PPS	O	—	Comparator 1 Output
C2OUT	PPS	PPS	PPS	O	—	Comparator 2 Output
PMALL	30	44	A29	O	TTL/ST	Parallel Master Port Address Latch Enable Low Byte
PMALH	29	43	B24	O	TTL/ST	Parallel Master Port Address Latch Enable High Byte
PMA0	30	44	A29	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA1	29	43	B24	O	TTL/ST	Parallel Master Port Address bit 0 Input (Buffered Slave modes) and Output (Master modes)
PMA2	8	14	A9	O	TTL/ST	Parallel Master Port data (Demultiplexed Master mode) or Address/Data (Multiplexed Master modes)
PMA3	6	12	A8	O	TTL/ST	
PMA4	5	11	B6	O	TTL/ST	
PMA5	4	10	A7	O	TTL/ST	
PMA6	16	29	B17	O	TTL/ST	
PMA7	22	28	A21	O	TTL/ST	
PMA8	32	50	A32	O	TTL/ST	
PMA9	31	49	B27	O	TTL/ST	
PMA10	28	42	A28	O	TTL/ST	
PMA11	27	41	B23	O	TTL/ST	
PMA12	24	35	B20	O	TTL/ST	
PMA13	23	34	A24	O	TTL/ST	
PMA14	45	71	A46	O	TTL/ST	
PMA15	44	70	B38	O	TTL/ST	
PMCS1	45	71	A46	O	TTL/ST	
PMCS2	44	70	B38	O	TTL/ST	
PMD0	60	93	B52	I/O	TTL/ST	
PMD1	61	94	A64	I/O	TTL/ST	
PMD2	62	98	A66	I/O	TTL/ST	

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
P = Power
I = Input

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUS

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX330/350/370/430/450/470 family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.8 "External Oscillator Pins"**)

The following pins may be required:

VREF+/VREF- pins, used when external voltage reference for the ADC module is implemented.

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) DS50001765
- *"MPLAB® ICD 3 Design Advisory"* DS50001764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS50001616
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) DS50001749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

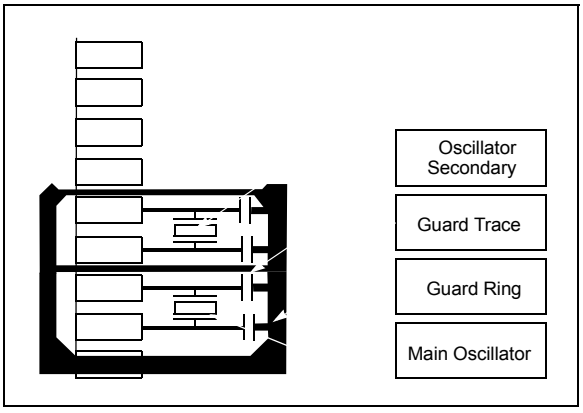
The trace pins can be connected to a hardware trace-enabled programmer to provide a compressed real-time instruction trace. When used for trace, the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



2.9 Unused I/Os

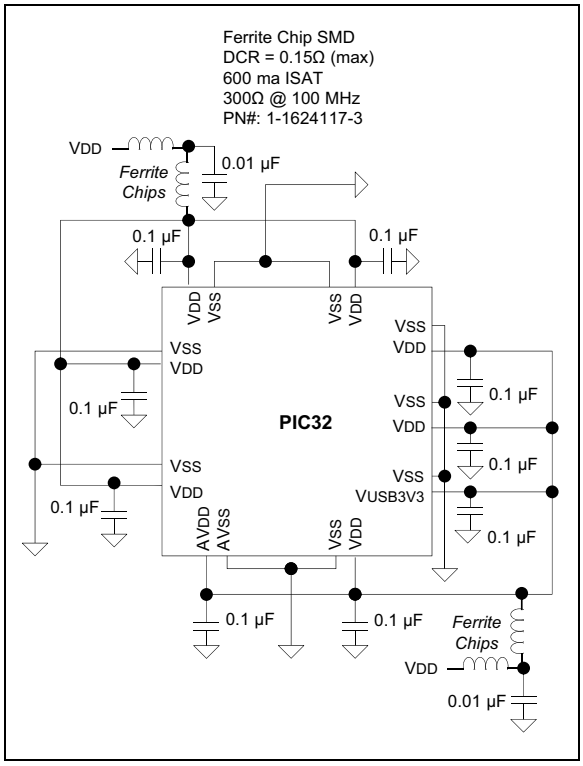
Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternatively, inputs can be reserved by connecting the pin to VSS through a 1k to 10k resistor and configuring the pin as an input.

2.10 EMI/EMC/EFT (IEC 61000-4-4 and IEC 61000-4-2) Suppression Considerations

The use of LDO regulators is preferred to reduce overall system noise and provide a cleaner power source. However, when utilizing switching Buck/ Boost regulators as the local power source for PIC32 devices, as well as in electrically noisy environments or test conditions required for IEC 61000-4-4 and IEC 61000-4-2, users should evaluate the use of T-Filters (i.e., L-C-L) on the power pins, as shown in Figure 2-5. In addition to a more stable power source, use of this type of T-Filter can greatly reduce susceptibility to EMI sources and events.

FIGURE 2-5: EMI/EMC/EFT SUPPRESSION CIRCUIT



REGISTER 10-7: DCHxCON: DMA CHANNEL 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	CHBUSY	—	—	—	—	—	—	CHCHNS(1)
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R-0	R/W-0	R/W-0
	CHEN(2)	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **CHBUSY:** Channel Busy bit
- 1 = Channel is active or has been enabled
- 0 = Channel is inactive or has been disabled

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **CHCHNS:** Chain Channel Selection bit(1)
- 1 = Chain to channel lower in natural priority (CH1 will be enabled by CH2 transfer complete)
- 0 = Chain to channel higher in natural priority (CH1 will be enabled by CH0 transfer complete)

bit 7 **CHEN:** Channel Enable bit(2)
- 1 = Channel is enabled
- 0 = Channel is disabled

bit 6 **CHAED:** Channel Allow Events If Disabled bit
- 1 = Channel start/abort events will be registered, even if the channel is disabled
- 0 = Channel start/abort events will be ignored if the channel is disabled

bit **CHCHN:** Channel Chain Enable bit
- 1 = Allow channel to be chained
- 0 = Do not allow channel to be chained

bit 4 **CHAEN:** Channel Automatic Enable bit
- 1 = Channel is continuously enabled, and not automatically disabled after a block transfer is complete
- 0 = Channel is disabled on block transfer complete

bit 3 **Unimplemented:** Read as '0'

bit 2 **CHEDET:** Channel Event Detected bit
- 1 = An event has been detected
- 0 = No events have been detected

bit 1-0 **CHPRI<1:0>:** Channel Priority bits
- 11 = Channel has priority 3 (highest)
- 10 = Channel has priority 2
- 01 = Channel has priority 1
- 00 = Channel has priority 0

Note 1: The chain selection bit takes effect when chaining is enabled (i.e., CHCHN = 1).

2: When the channel is suspended by clearing this bit, the user application should poll the CHBUSY bit (if available on the device variant) to see when the channel is suspended, as it may take some clock cycles to complete a current transaction before the channel is suspended.

REGISTER 11-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER (CONTINUED)

bit 1 **CRC5EF:** CRC5 Host Error Flag bit(4)
1 = Token packet is rejected due to CRC5 error
0 = Token packet is accepted
EOFEF: EOF Error Flag bit(3,5)
1 = EOF error condition is detected
0 = No EOF error condition

bit 0 **PIDEF:** PID Check Failure Flag bit
1 = PID check is failed
0 = PID check is passed

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

NOTES:

REGISTER 18-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 4 **DISSDI:** Disable SDI bit
1 = SDI pin is not used by the SPI module (pin is controlled by PORT function)
0 = SDI pin is controlled by the SPI module

bit 3-2 **STXISEL<1:0>:** SPI Transmit Buffer Empty Interrupt Mode bits
11 = Interrupt is generated when the buffer is not full (has one or more empty elements)
10 = Interrupt is generated when the buffer is empty by one-half or more
01 = Interrupt is generated when the buffer is completely empty
00 = Interrupt is generated when the last transfer is shifted out of SPISR and transmit operations are complete

bit 1-0 **SRXISEL<1:0>:** SPI Receive Buffer Full Interrupt Mode bits
11 = Interrupt is generated when the buffer is full
10 = Interrupt is generated when the buffer is full by one-half or more
01 = Interrupt is generated when the buffer is not empty
00 = Interrupt is generated when the last word in the receive buffer is read (i.e., buffer is empty)

Note 1: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

20.2 Timing Diagrams

Figure 20-2 and Figure 20-3 illustrate typical receive and transmit timing for the UART module.

FIGURE 20-2: UART RECEPTION

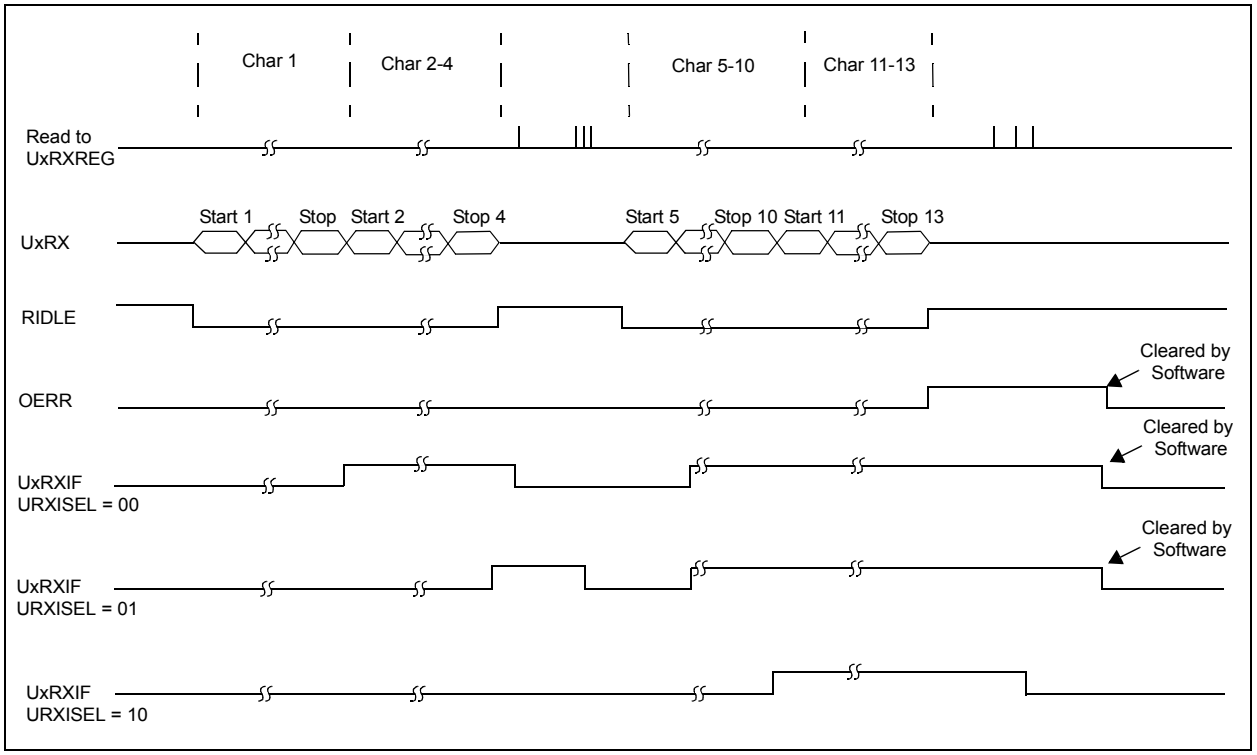
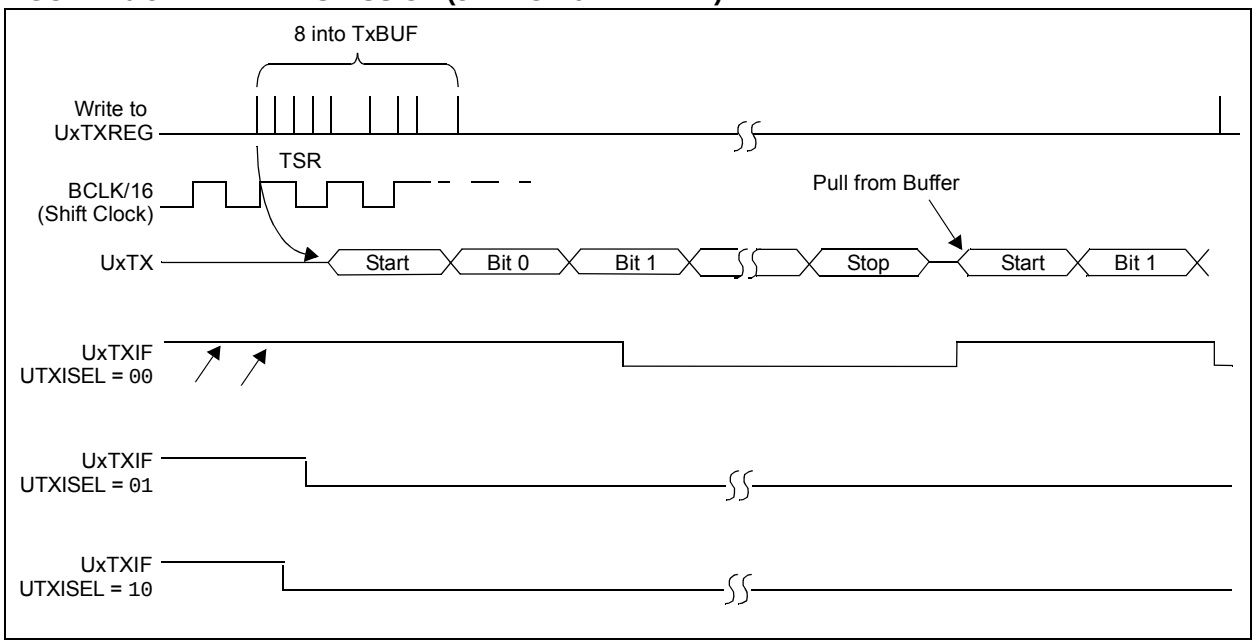


FIGURE 20-3: TRANSMISSION (8-BIT OR 9-BIT DATA)



21.1 Control Registers

TABLE 21-1: PARALLEL MASTER PORT REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
7000	PMCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	ADRMUX<1:0>		PMPTTL	PTWREN	PTRDEN	CSF<1:0>		ALP	CS2P	CS1P	—	WRSP	RDSP	0000
7010	PMMODE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BUSY	IRQM<1:0>		INCM<1:0>		MODE16	MODE<1:0>		WAITB<1:0>		WAITM<3:0>				WAITE<1:0>		0000
7020	PMADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CS2	CS1	ADDR<13:0>														0000
7030	PMDOUT	31:16	DATAOUT<31:0>																0000
		15:0																	0000
7040	PMDIN	31:16	DATAIN<31:0>																0000
		15:0																	0000
7050	PMAEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PTEN<15:0>																0000
7060	PMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E	BFBF

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 23-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ 0, this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when ADC is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

TABLE 31-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage**	2.3	—	3.6	V	—
DC12	VDR	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	2.1	V	—
DC17	SVDD	**VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.00005	—	0.115	V/μs	—

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

TABLE 31-33: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

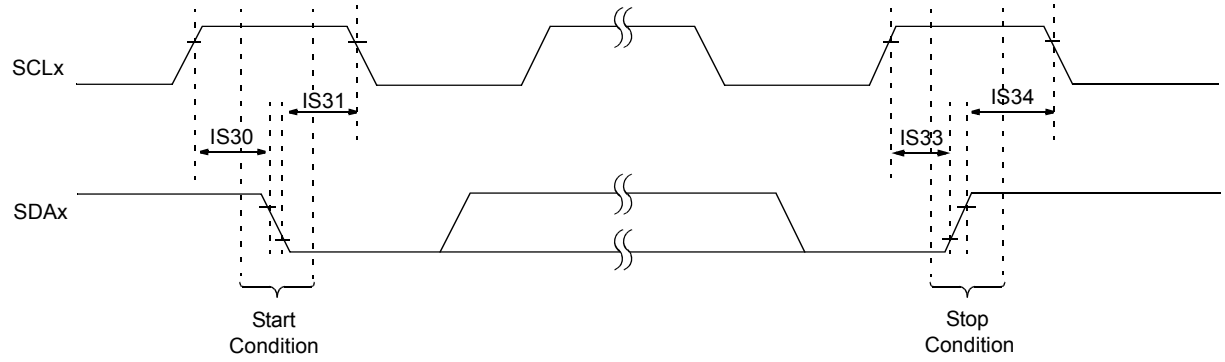
AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

FIGURE 31-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)



Note: Refer to Figure 31-1 for load conditions.

FIGURE 31-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)

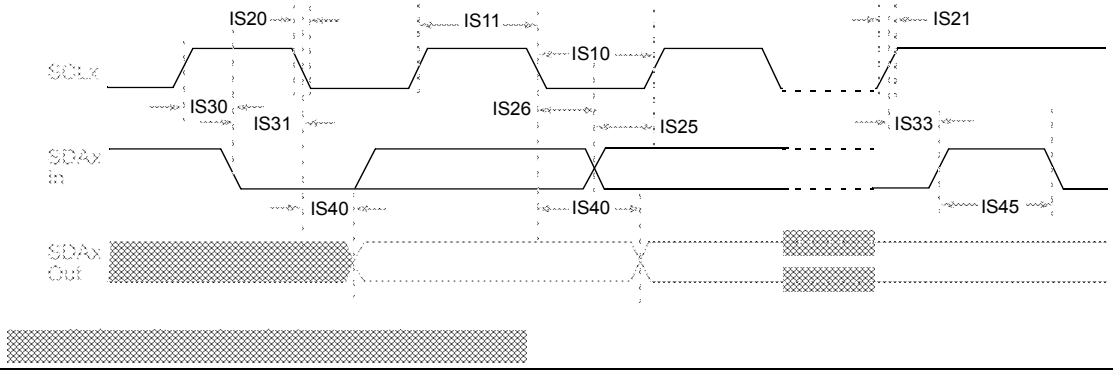


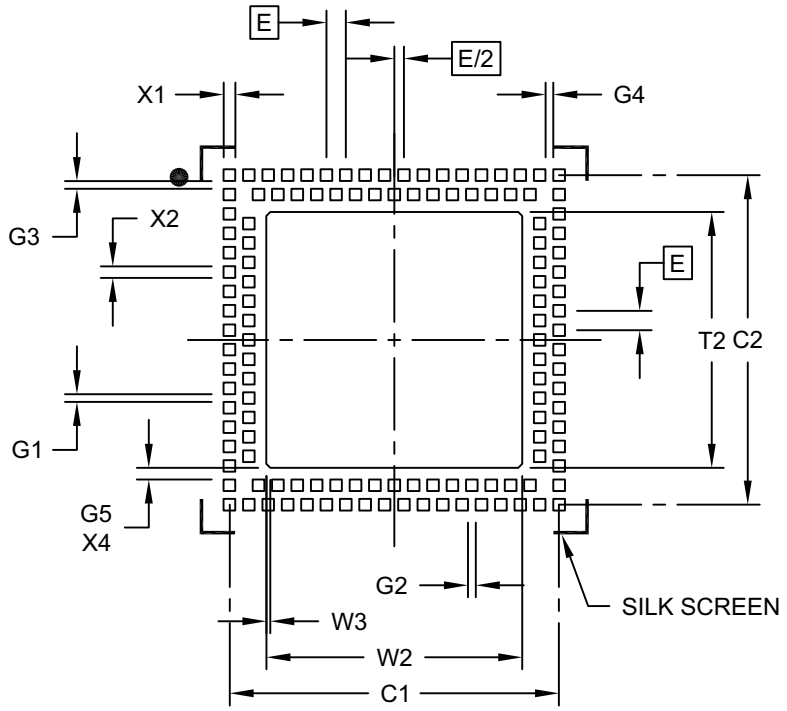
TABLE 31-34: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.**	**Max.**	**Units**	**Conditions**
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode **(Note 1)**	250		ns	
IS40	TAA:SCL	Output Valid from Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode **(Note 1)**	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode **(Note 1)**	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

124-Very Thin Leadless Array Package (TL) – 9x9x0.9 mm Body [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Pad Clearance	G1	0.20		
Pad Clearance	G2	0.20		
Pad Clearance	G3	0.20		
Pad Clearance	G4	0.20		
Contact to Center Pad Clearance (X4)	G5	0.30		
Optional Center Pad Width	T2			6.60
Optional Center Pad Length	W2			6.60
Optional Center Pad Chamfer (X4)	W3		0.10	
Contact Pad Spacing	C1		8.50	
Contact Pad Spacing	C2		8.50	
Contact Pad Width (X124)	X1			0.30
Contact Pad Length (X124)	X2			0.30

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2193A

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